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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**In the Title:**

The Title has been amended as follows,

[Application of Pressure Sensitive Adhesive (PSA) to Pre-Attach Thermal Interface Film/Tape To Cooling Device]

**Adhesive To Attach A Cooling Device To A Thermal Interface**

**In the Specification:**

The following has been added to the first sentence of the Specification:

**This application is a continuation patent application of Application Serial No. 09/158,227, entitled *Application of Pressure Sensitive Adhesive (PSA) to Pre-attach Thermal Interface Film/Tape to Cooling Device*, and filed on September 22, 1998.**

The paragraph beginning at page 9, line 24 has been amended as follows:

Next, thermal interface 102, with PSA strips 104 applied near edges [118] thereof, is attached to a surface 104 of base plate 120 as illustrated in **Figure 5**. The attachment is mainly due to an adhesive surface of PSA 104 that makes contact with surface 140 of base plate 120. Note that PSA 104 is compliable, becoming very thin when thermal interface 102 is pressed and attached to base plate 120 of heat sink 118. Heat may be transferred from the integrated circuit package 116 to the heat sink 118 mainly via heat transfer area 106, demarcated by dotted lines 112 and 114. Heat transfer area 106 is not covered by PSA 104. The vendor of the heat sink may then ship the assembly, including the heat sink 118 with the thermal interface 102 attached thereto, to the manufacturer of

the integrated circuit package, for further assembling the integrated circuit package 116 to the assembly.

In the claims:

Claims 1-19 are cancelled.

Claims 54-73 are new.